

### ABSTRACT

The invention is directed to a chemical-mechanical polishing pad comprising a porous polymeric material, wherein the porous polymeric material has a Poisson's ratio less than 0. The invention further provides a method of polishing a workpiece comprising (i) providing a workpiece to be polished, (ii) contacting the workpiece with a chemical-mechanical polishing system comprising the polishing pad of the invention, and (iii) abrading at least a portion of the surface of the workpiece with the polishing system to polish the workpiece.